



Material Content Data Sheet



Sales Product Name		IPB120N06S4-H1		Issued		25. September 2017		
MA#		MA000471414						
Package		PG-TO263-3-2		Weight*		1573.30 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	10.427	0.66	0.66	6628	6628
leadframe	non noble metal	iron	7439-89-6	0.304	0.02		193	
	inorganic material	phosphorus	7723-14-0	0.091	0.01		58	
	non noble metal	copper	7440-50-8	304.026	19.32	19.35	193240	193491
wire	non noble metal	aluminium	7429-90-5	98.600	6.27	6.27	62671	62671
encapsulation	organic material	carbon black	1333-86-4	8.923	0.57		5672	
	plastics	epoxy resin	-	98.155	6.24		62388	
	inorganic material	silicondioxide	60676-86-0	487.799	31.00	37.81	310047	378107
leadfinish	non noble metal	tin	7440-31-5	9.657	0.61	0.61	6138	6138
plating	non noble metal	nickel	7440-02-0	0.228	0.01		145	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.01	1	145
solder	noble metal	silver	7440-22-4	0.168	0.01		107	
	non noble metal	tin	7440-31-5	0.134	0.01		85	
	non noble metal	lead	7439-92-1	6.412	0.41	0.43	4076	4268
heatspreader	non noble metal	iron	7439-89-6	0.548	0.03		349	
	inorganic material	phosphorus	7723-14-0	0.165	0.01		105	
	non noble metal	copper	7440-50-8	547.666	34.82	34.86	348097	348552
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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